

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to:  
Assistant Commissioner for Patents, Washington, D.C. 20231 on

5-26-98  
Date of Deposit

William A. Webb, Reg. No. 28,277

Name of Applicant, assignee or  
Registered Representative

[Signature]  
Signature

Our Case No. 7103/30

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:

Homayoun Talieh and David E. Weldon

Serial No.: 08/853,323

Filing Date: May 8, 1997

For Linear Polisher and Method for  
Semiconductor Wafer Planarization

Examiner: George Nguyen

Group Art Unit No. 3203

**RECEIVED**

**JUN - 8 1998**

**GROUP 3200**

**AMENDMENT**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

Please enter the following amendments in response to the Office Action of  
February 26, 1998.

**In the Claims**

Please cancel Claims 1-22, 33 and 35 without prejudice, please amend Claims  
32 and 34 as follows, and please enter new Claims 36-43 as follows:

32. (Amended) A polishing pad assembly for polishing a semiconductor

06/05/1998 ATW:fer 08/05/1998 08/05/1998

01 FC:102

328.00 NP

*Handwritten:* SMDI/C

*Handwritten:* #6 @  
Amended Sub Specs  
H Chapman  
6-10-98

